

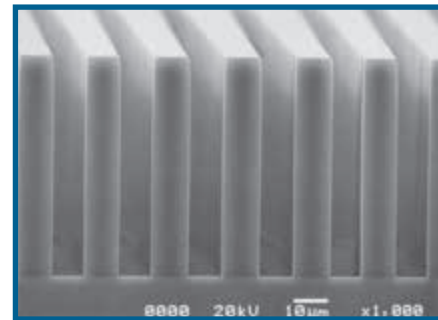
KMPR[®] 1000

Chemically Amplified Negative Photoresist

MICRO CHEM

NIPPON KAYAKU

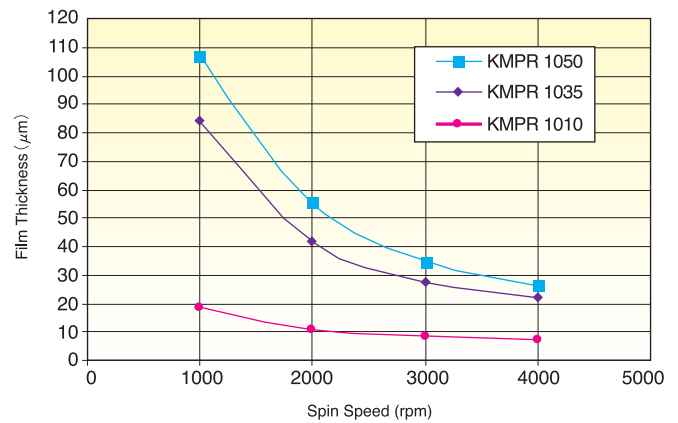
KMPR[®] 1000 i-Line photoresist is a high contrast, epoxy based photoresist that can be developed in a conventional aqueous alkaline developer (TMAH) and readily stripped from the wafer. KMPR[®] 1000 has excellent adhesion, chemical and plasma resistance, making it ideal for many MEMS, Electrolytic Plating and DRIE applications.



i-line mask aligner
10 μm features, 60 μm KMPR coating

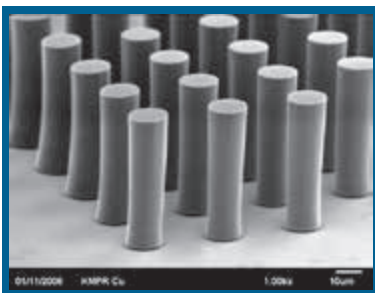
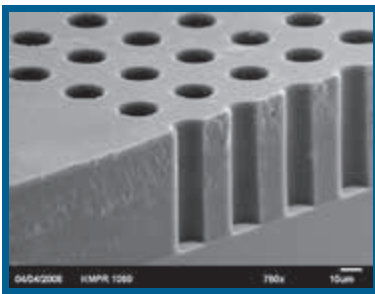
Features

- 6-120 μm film thickness in a single coat
- Aqueous developer compatible (2.38% TMAH)
- Wet strips in conventional strippers
- High aspect ratio imaging
- Excellent plating resistance
- Excellent dry etch resistance

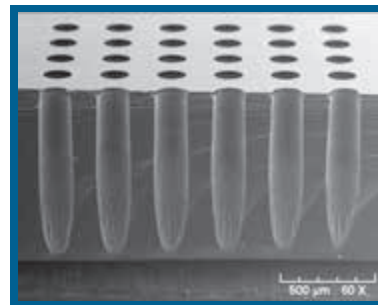


Example of use

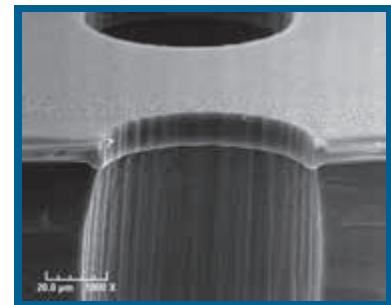
Mold for Cu electroplating



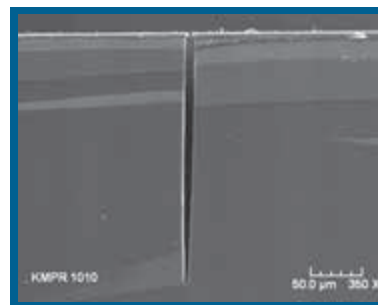
DRIE (Bosch process)



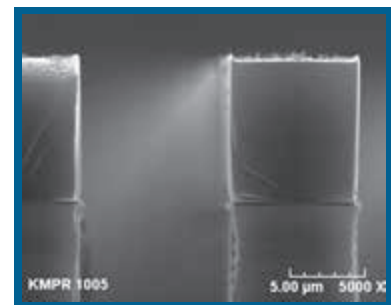
980 μm DRIE (1)



980 μm DRIE (2)



200 μm DRIE



Hard baked KMPR post etch

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